
Mechanical standardization of semiconductor devices - Part 6-5: General rules for the preparation of outline drawings of surface mounted semiconductor device package - Design guide for fine-pitch ball grid array (FBGA) (IEC 60191-6-5:2001)

Mechanical standardization of semiconductor devices -- Part 6-5: General rules for the preparation of outline drawings of surface mounted semiconductor device packages - Design guide for fine-pitch ball grid array (FBGA)

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Mechanische Normung von Halbleiterbauelemente -- Teil 6-5: Allgemeine Regeln für die Erstellung von Gehäusezeichnungen von SMD-Halbleitergehäusen - Konstruktionsleitfaden für Feinraster-Ball-Grid-Arrays (FBGA)

[SIST EN 60191-6-5:2002](https://standards.iteh.ai/catalog/standards/sist/8c8fa714-a87c-4ac6-aae6-10201f068300/sist-en-60191-6-5-2002)

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Normalisation mécanique des dispositifs à semiconducteurs -- Partie 6-5: Règles générales pour la préparation des dessins d'encombrement des dispositifs à semiconducteurs à montage en surface - Guide de conception pour les boîtiers matriciels à billes et à pas fins (FBGA)

Ta slovenski standard je istoveten z: EN 60191-6-5:2001

ICS:

01.100.25	Risbe s področja elektrotehnike in elektronike	Electrical and electronics engineering drawings
31.080.01	Polprevodniški elementi (naprave) na splošno	Semiconductor devices in general
31.240	Mehanske konstrukcije za elektronsko opremo	Mechanical structures for electronic equipment

SIST EN 60191-6-5:2002**en**

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EUROPEAN STANDARD

EN 60191-6-5

NORME EUROPÉENNE

EUROPÄISCHE NORM

October 2001

ICS 31.080.01

English version

Mechanical standardization of semiconductor devices
Part 6-5: General rules for the preparation of outline drawings of
surface mounted semiconductor device packages -
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Normalisation mécanique des dispositifs
à semiconducteurs
Partie 6-5: Règles générales pour
la préparation des dessins
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(CEI 60191-6-5:2001)

Mechanische Normung von
Halbleiterbauelemente
Teil 6-5: Allgemeine Regeln für
die Erstellung von Gehäusezeichnungen
von SMD-Halbleitergehäusen -
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Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the Central Secretariat or to any CENELEC member.

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CENELEC members are the national electrotechnical committees of Austria, Belgium, Czech Republic, Denmark, Finland, France, Germany, Greece, Iceland, Ireland, Italy, Luxembourg, Malta, Netherlands, Norway, Portugal, Spain, Sweden, Switzerland and United Kingdom.

CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

Central Secretariat: rue de Stassart 35, B - 1050 Brussels

Foreword

The text of document 47D/437/FDIS, future edition 1 of IEC 60191-6-5, prepared by SC 47D, Mechanical standardization of semiconductor devices, of IEC TC 47, Semiconductor devices, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 60191-6-5 on 2001-10-01.

The following dates were fixed:

- latest date by which the EN has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2002-07-01
- latest date by which the national standards conflicting with the EN have to be withdrawn (dow) 2004-10-01

Annexes designated "normative" are part of the body of the standard.
In this standard, annex ZA is normative.
Annex ZA has been added by CENELEC.

Endorsement notice

The text of the International Standard IEC 60191-6-5:2001 was approved by CENELEC as a European Standard without any modification.

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Annex ZA (normative)

Normative references to international publications with their corresponding European publications

This European Standard incorporates by dated or undated reference, provisions from other publications. These normative references are cited at the appropriate places in the text and the publications are listed hereafter. For dated references, subsequent amendments to or revisions of any of these publications apply to this European Standard only when incorporated in it by amendment or revision. For undated references the latest edition of the publication referred to applies (including amendments).

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60191-6	1990	Mechanical standardization of semiconductor devices Part 6: General rules for the preparation of outline drawings of surface mounted semiconductor device packages	-	-

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INTERNATIONAL STANDARD

IEC 60191-6-5

First edition
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Mechanical standardization of semiconductor devices –

Part 6-5: General rules for the preparation of outline drawings of surface mounted semiconductor device packages – Design guide for fine-pitch ball grid array (FBGA)

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Normalisation mécanique des dispositifs à semiconducteurs

*Partie 6-5:
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d'encombrement des dispositifs à semiconducteurs
à montage en surface –
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International Electrotechnical Commission
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INTERNATIONAL ELECTROTECHNICAL COMMISSION

MECHANICAL STANDARDIZATION OF SEMICONDUCTOR DEVICES –**Part 6-5: General rules for the preparation of outline drawings
of surface mounted semiconductor device packages –
Design guide for fine-pitch ball grid array (FBGA)**

FOREWORD

- 1) The IEC (International Electrotechnical Commission) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of the IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, the IEC publishes International Standards. Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. The IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
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International Standard IEC 60191-6-5 has been prepared by subcommittee 47D: Mechanical standardization of semiconductor devices, of IEC technical committee 47: Semiconductor devices.

The text of this standard is based on the following documents:

FDIS	Report on voting
47D/437/FDIS	47D/455/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 3.

The committee has decided that the contents of this publication will remain unchanged until 2003. At this date, the publication will be

- reconfirmed;
- withdrawn;
- replaced by a revised edition; or
- amended.

A bilingual version of this publication may be issued at a later date.

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